

PATENT  
Docket No. 150.01280105

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s):	Brian A. Vaartstra et al.	)	Group Art Unit:	2815
		)		
Serial No.:	09/603,132	)	Examiner:	Eugene Lee
Confirmation No.:	3538	)		
		)		
Filed:	23 June 2000	)		
		)		
For:	DEVICE STRUCTURES INCLUDING RUTHENIUM SILICIDE DIFFUSION BARRIER LAYERS			

## "FEE ADDRESS" INDICATION FORM

Commissioner for Patents  
Mail Stop Issue Fee  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:


Please recognize as the "Fee Address" under the provisions of 37 C.F.R. §1.363 the following address:

Micron Technology, Inc.  
8000 South Federal Way  
P.O. Box 6  
Boise, Idaho 83707-0006

Customer Number 26809

in the following listed application(s) or patent(s) for which the Issue Fee has been paid.

PATENT NUMBER	SERIAL NUMBER	PATENT DATE	U.S. FILING DATE
	09/603,132		June 23, 2000

Typed name of person signing Loren D. Albin  
Signed   
Date June 9, 2009

(check one) \_\_\_\_\_ Owner of record  
X Owner's attorney or agent of record Reg No. 37,763